

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

Listing of Claims:

1. (Currently Amended) A wiring-terminal-connecting adhesive, adapted to be used to electrically connect wiring terminals by interposing said adhesive between wiring substrates which are disposed so that said wiring terminals on faces of respective wiring substrates face each other, and heating said wiring substrates under application of a pressure, comprising

a curing agent capable of generating a free radical upon heating;

a radically polymerizable substance;

silicone particles having a modulus of elasticity of from 0.1 MPa to 100 MPa at 25°C and an average particle diameter of from 0.1 µm to 20 µm; and

electrically conductive particles,

wherein said adhesive has a modulus of elasticity of from 100 to 3,000 MPa at 25°C after curing.

2. (Original) The adhesive according to claim 1, wherein said silicone particles are contained in an amount of from 5 parts by weight to 200 parts by weight based on the weight of said radically polymerizable substance.

3. (Original) The adhesive according to claim 1, which further comprises a film-forming material.

4. (Original) The adhesive according to claim 3, wherein said film-forming material is a phenoxy resin.

5. (Previously Presented) The wiring-connecting-connecting adhesive according to claim 3, wherein said silicone particles are contained in an amount of from 5 parts by weight to 200 parts by weight based on 100 parts by weight of the total of said radically polymerizable substance and said film-forming material.

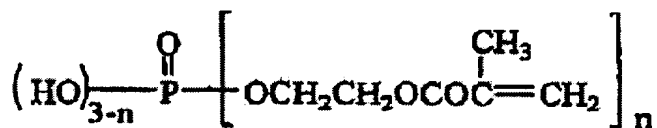
6.-17. (Cancelled)

18. (Previously Presented) The wiring-terminal-connecting adhesive according to claim 4, wherein said silicone particles are contained in an amount of from 5 parts by weight to 200 parts by weight based on 100 parts by weight of the total of said radically polymerizable substance and said film-forming material.

19.-24. (Cancelled)

25. (Previously Presented) The adhesive according to claim 1, wherein said electrically conductive particles have at least one of gold, silver, Ni, Cu, solder, carbon and a platinum group metal at least at the surface thereof.

26. (Previously Presented) The adhesive according to claim 1, wherein the radically polymerizable substance includes, as a part thereof, a radically polymerizable substance having a phosphoric ester structure represented by the following chemical formula (1)



(1)

wherein n is 1, 2 or 3.

27. (Previously Presented) The adhesive according to claim 1, wherein said electrically conductive particles have at least one of gold, silver and a platinum group metal at least at the surface thereof.

28. (Previously Presented) The adhesive according to claim 1, wherein said electrically conductive particles are included in the adhesive in an amount of 0.1 to 30 parts by volume of resin component of the adhesive.

29. (Previously Presented) The adhesive according to claim 1, having a flowability of 1.3 to 3.0 as a value of flowability (B)/(A) represented by initial area (A) and the area (B) after heating and pressing, at 150°C and 2 MPa for 10 second, an adhesive 35 μm in thickness and 5mm x 5mm in size interposed between two sheets of glass of 0.7 mm in thickness and 15 mm x 15 mm in size.

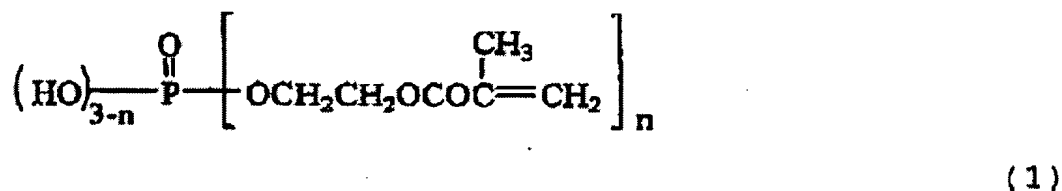
30. (Cancelled)

31. (New) A wiring-terminal-connecting adhesive, adapted to be used to electrically connect wiring terminals by interposing said adhesive between wiring

substrates which are disposed so that said wiring terminals on faces of respective wiring substrates face each other, and heating said wiring substrates under application of a pressure, comprising

a curing agent capable of generating a free radical upon heating;

a radically polymerizable substance, wherein the radically polymerizable substance includes, as a part thereof, a radically polymerizable substance having a phosphoric ester structure represented by the following chemical formula (1)



wherein n is 1, 2 or 3;

silicone particles having a modulus of elasticity of from 0.1 MPa to 100 MPa at 25°C and an average particle diameter of from 0.1 μm to 20 μm; and electrically conductive particles.

32. (New) A wiring-terminal-connecting adhesive, adapted to be used to electrically connect wiring terminals by interposing said adhesive between wiring substrates which are disposed so that said wiring terminals on faces of respective wiring substrates face each other, and heating said wiring substrates under application of a pressure, comprising

a curing agent capable of generating a free radical upon heating;

a radically polymerizable substance;

silicone particles having a modulus of elasticity of from 0.1 MPa to 100 MPa at 25°C and an average particle diameter of from 0.1 μm to 20 μm ; and

electrically conductive particles,

wherein the adhesive has a flowability of 1.3 to 3.0 as a value of flowability (B)/(A) represented by initial area (A) and the area (B) after heating and pressing, at 150°C and 2 MPa for 10 second, an adhesive 35 μm in thickness and 5mm x 5mm in size interposed between two sheets of glass of 0.7 mm in thickness and 15 mm x 15 mm in size.